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(54) Title: COMPOSITION FOR METAL PLATING COMPRISING SUPPRESSING AGENT FOR VOID FREE SUBMICRON FEATURE FILLING

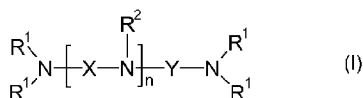
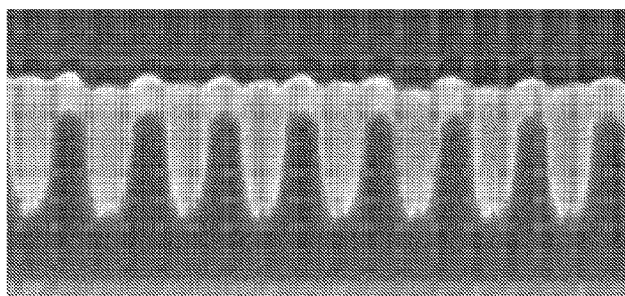


Fig. 6



(57) Abstract: A composition for filling submicrometer sized features having an aperture size of 30 nanometers or less comprising a source of copper ions, and at least one suppressing agent selected from compounds of formula (I) wherein - the R1 radicals are each independently selected from a copolymer of ethylene oxide and at least one further C3 to C4 alkylene oxide, said copolymer being a random copolymer. - the R2 radicals are each independently selected from R1 or alkyl. - X and Y are spacer groups independently, and X for each repeating unit independently, selected from C1 to C6 alkylene and Z-(O-Z)m wherein the Z radicals are each independently selected from C2 to C6 alkylene, - n is an integer equal to or greater than 0. - m is an integer equal to or greater than 1.



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